	1	2	3	4	5	6
	Product Name:	ZX050C-WLB1818 (X1-WLB1818-	4 U-WLB1818-4) Characterizati	ion testing bringup breakout me	odule	
F	Product Description:	High Speed characterization module under test, U1, is accessible via 2 de	e meeting 10GHz signal bandwidt edicated SMA connectors for exte	h with < 0.3dB insertion loss. Eac ernal stimulus as well as measure	ch pin of the device ment purpose.	
		ZX050C-WLB1818 is designed for A device. ZX50C-WLB1818 is design gold plated SMA connectors.	SIC (IC) characterization, functied with 50 Ω (Ohms) trace imperiately of the trace of th	onal testing of X1-WLB1818-4 U- dance using 4 layer PCB. The mo	WLB1010-4 packaged dule includes 35µ	
		Ideal evaluation, bringup, and testin U-WLB1818-4 footprint package.	g of any discrete component such	n as ESD diode, sensor, or any IC	using X1-WLB1818,	1.9
_		Available Rxy to GND on each U1 p any standard 0402 device as require	in (xy is the U1 pin number). Rx ed, resistor, capacitor, bead	ky is unpopulated 0402 SMD foot	print. User may apply	
		Available GND test point header pin	interfacing with the module's GN	D plane & GND fills		
	Application:	Bringup, Characterization, testing, c	levelopment, modular design eval	luations	Simplified Blo	ck Diagram
	Target DUT :	Designed specifically for any WLB1 SMD device with SMA connectors a	818-4(X1-WLB1818 and U-WLB ccessing all pins of the WLB1818	31010-4) 3		
5	Pitch:	Standard WLB1818 (X1-WLB1818	, U-WLB1818-4)SMD package o	or equivalent		
	Headers:	Ground access test point (GND) - 0.	025" SQ with 0.32" (5.6mm) post	height		
	DUT landing pads:	Surface Mount, 4 pin package – WL	B1818-4(X1-WLB1818,U-WLE	31010-4) or equivalent	SMA B1	
	WLB1818-4 DIMENTI	ONS (mm)				
	UNIT b	e D E 700 1.800 1.80	0			RB2

Pad Layout

0b (X4)

mm	typical min	0.3000 0.2700	0.650	1.790 1.780	1.790 1.780	
	E Version		REFER	ENCES		
		IEC JEDEC	JEITA			
U-WI	U-WLB1818-4					
X1-W	LB1818-4					

MIL-STD-202, Method 213

≤3mΩ

≤2mΩ

≥5000MΩ

≤1.15 (0.8-2.5G)

50Ω

Frequency Range: DC – 12GHz

Working Voltage: 335V max

Withstand Voltage: 1000V rms

-65°C +165°C

С

В

SMA:

Impedance:

Vibration:

Temp Range:

Center Contact:

Outer Contact:

VSWR Straight:

Notice

Insulation resistance:

Rxy (RA1, RA2, RB1, RB2) are unpopulated 0402 SMD package footprint	II⊣ ● SMA	
		10.5

PLUG (P))		
	1/ J	4-36	

JACK (J)



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0b (X4)

PIN ID

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2

2

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HECKED:		DRAWN:		REVISSION: 1.0	
M. MARI	INA	SLAVIK	<u> </u>	SHEET: 1 OF 1	
	7			8	